Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.066”**

****

**.066”**

**Top Material: Al**

**Backside Material:Ti/Ni/Ag**

**Bond Pad Size: E= .008 x .015”**

 **B= .009”**

**Backside Potential: COLLECTOR**

**Mask Ref: M13-D**

**APPROVED BY: DK DIE SIZE .066” X .066” DATE: 6/8/22**

**MFG: ZETEX THICKNESS .011” P/N: 2N6193**

**DG 10.1.2**

#### Rev B, 7/19/02